

CIN::APSE® Technology

Characteristics Overview

Standard Offering

Diameter *Not sold as a loose contact	0.020in (0.508mm) & 0.040in (1.016mm)
Contact Material	Gold-Plated Molybdenum

Technical Specifications

Applications	IC to PCB (LGA), PCB to PCB, Flex to PCB
Contact Pitch	≤ 0.04in (≤ 1.00mm)
Current Capability	3 Amps Continuous
Temperature Range	-75°F (-60°C) to 220°F (105°C)
Compliance Total	.006 Max
Compression Force / Contact	3oz (85g) / Contact
Crosstalk / Bandwidth	-25dB @ 10GHz
Insertion Loss / Bandwidth (S21)	-0.2dB @ 10GHz -1.2dB @ 20GHz -0.32nH / 0.01nH
Return Loss / Bandwidth (S11)	-19dB @ 10GHz
Self / Mutual Inductance	0.06pF / 0.011pF
Ground / Mutual Capacitance	0.06pF / 0.011pF
Resistance	<10mW

Markets

- Aerospace
- Military
- Communications
- Datacom
- Medical

Applications

- Interconnects
- Connectors
- Test Fixtures
- Grounding
- EMI Shielding
- Semiconductor
- RF /Coaxial
- IC Sockets
- Mezzaine Connectors
- Interposers

Custom Programs

- Satellites
- Missiles
- Space Probes
- Product Test
- UAV / UAS
- Millimeter Wave
- Radar Arrays
- Chip Packaging
- GHz Connectors

